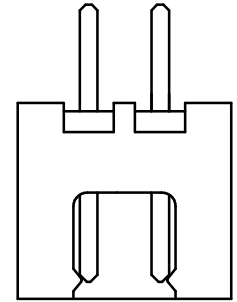
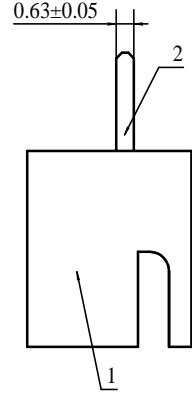
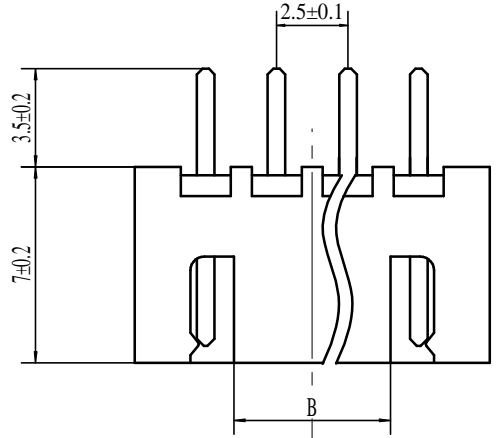


REV.	EC#	DESCRIPTION	DATE	DRAWN	CHECK	APPROVED
1.00		初版发行	2020-8-28	瞿寿坤	胡海萍	胡海萍

NUMBER OF PINS	DIM.A	DIM.B
15P	40	33.1
14P	37.5	30.6
13P	35	28.1
12P	32.5	25.6
11P	30	23.1
10P	27.5	20.6
9P	25	18.1
8P	22.5	15.6
7P	20	13.1
6P	17.5	10.6
5P	15	8.1
4P	12.5	5.6
3P	10	3.1
2P	7.5	0



2PIN

适应基板厚度: 1.2mm~1.6mm

温度范围: -25℃~85℃

额定电压: 250V AC/DC

额定电流: 3A

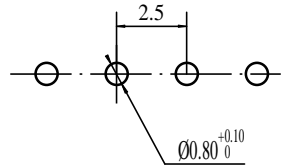
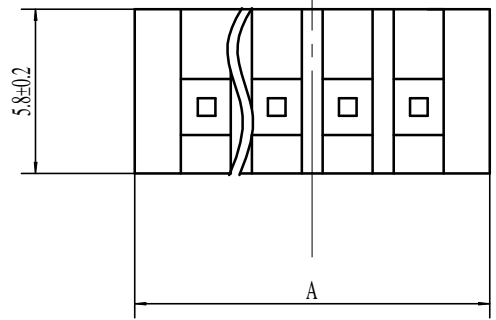
接触电阻: <= 0.01Ω

绝缘电阻: >= 1000MΩ

耐压: 1000V AC/minute

技术要求:

- 1) 材质:见附表;
- 2) 电镀:见附表;
- 3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
- 4) 端子表面无氧化、电镀不良等现象。



PCB LAYOUT

GENERAL TOLERANCES			
DIM	TOL	DIM	DEG
X		X°	±3.00°
X.X	±0.35	X.X°	±2.00°
X.XX	±0.25	X.XX°	±1.00°
X.XXX	±0.15	X.XXX°	

2	PIN	n PCS	材质:黄铜,电镀:镀亮锡60u"MIN
1	Housing	1 PCS	材质:PA66 颜色:本色
NO.	NAME	QTY	DESCRIPTION
深圳市虹成电子有限公司			
DRAW:	瞿寿坤	2020-8-28	TITLE: WAFER 2.5XHA 立式 DIP
DESIGN:	瞿寿坤	2020-8-28	DRAW NAME: HCZZ0126-4
CHECK:	胡海萍	2020-8-28	SERIES: 1501 SERIES
APPROVED	胡海萍	2020-8-28	P/N:
CUSTOMER DRAWING			REV. 1.00 SCALE N/A
UNIT: mm		SHEET: 1/1	☉